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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM, WDT
Number of I/O	5
Program Memory Size	2KB (2K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 5x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.154", 3.90mm Width)
Supplier Device Package	8-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st7foxa0m6

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2 Pin description







3 Register and memory mapping

As shown in *Figure 3*, the MCU is capable of addressing 64 Kbytes of memories and I/O registers.

The available memory locations consist of 128 bytes of register locations, 128 bytes of RAM and 2 Kbytes of Flash program memory. The RAM space includes up to 64 bytes for the stack from C0h to FFh.

The highest address bytes contain the user reset and interrupt vectors.

The Flash memory contains two sectors (see *Figure 3*) mapped in the upper part of the ST7 addressing space so the reset and interrupt vectors are located in Sector 0 (FFE0h-FFFFh).

The size of Flash Sector 0 and other device options are configurable by option bytes (refer to Section 13.1 on page 110).

Caution: Memory locations marked as "Reserved" must never be accessed. Accessing a reserved area can have unpredictable effects on the device.



Figure 3. ST7FOXA0 memory map

Table 3.	ST7FOXA0 Hardware register map ⁽¹⁾
----------	---

Address	Block	Register label	Register name	Reset status	Remarks
0000h 0001h 0002h	Port A	PADR PADDR PAOR	Port A Data Register Port A Data Direction Register Port A Option Register	00h ⁽²⁾ 08h 02h ⁽³⁾	R/W R/W R/W
0003h to 000Ah			Reserved area (8 bytes)		



below 2mA at 5V. If PA3 is used as output push-pull, then the application must be switched off to allow the tool to take control of the RESET pin (PA3). To allow the programming tool to drive the RESET pin below V_{IL} , special care must also be taken when a pull-up is placed on PA3 for application reasons.

Caution: During normal operation the ICCCLK pin must be internally or externally pulled- up (external pull-up of 10 k Ω mandatory in noisy environment) to avoid entering ICC mode unexpectedly during a reset. In the application, even if the pin is configured as output, any reset will put it back in input pull-up.



Figure 4. Typical ICC Interface





4.7 Description of Flash Control/Status register (FCSR)

This register controls the XFlash erasing and programming using ICP, IAP or other programming methods.

1st RASS Key: 0101 0110 (56h)

2nd RASS Key: 1010 1110 (AEh)

When an EPB or another programming tool is used (in socket or ICP mode), the RASS keys are sent automatically.

Reset value: 000 0000 (00h)

7							0	
0	0	0	0	0	OPT	LAT	FGM	
Read/write								

Table 4. Flash register mapping and reset values

able 4.	Flash regis	ter mapp	ing and re	eset value	2S		<i>bl</i> ₀)~	
Address (Hex.)	Register label	7	6	5	40	3	2	1	
002Fh	FCSR Beset Value	- 0	- 0	5		- 0	OPT 0	LAT 0	P
	1	L	16						
			all'S						
			\sim						
		20							
	01	oqu							
	tepr	odu							
	etePr	odu							
0501	etePr	odu							
0501	etePr	odu							



5.3.1 Accumulator (A)

The Accumulator is an 8-bit general purpose register used to hold operands and the results of the arithmetic and logic calculations and to manipulate data.

5.3.2 Index registers (X and Y)

In indexed addressing modes, these 8-bit registers are used to create either effective addresses or temporary storage areas for data manipulation. (The Cross-Assembler generates a precede instruction (PRE) to indicate that the following instruction refers to the Y register.)

The Y register is not affected by the interrupt automatic procedures (not pushed to and popped from the stack).

5.3.3 Program Counter (PC)

The Program Counter is a 16-bit register containing the address of the post instruction to be executed by the CPU. It is made of two 8-bit registers PCL (Program Counter low which is the LSB) and PCH (Program Counter high which is the MSB).

5.3.4 Condition Code register (CC)

The 8-bit Condition Code register contains the interrupt mask and four flags representative of the result of the instruction just executed. This register can also be handled by the PUSH and POP instructions.

Reset value: 111x 1xxx



These bis can be individually tested and/or controlled by specific instructions.

Anthemetic management bits

Bit 4 = **H** Half carry bit

This bit is set by hardware when a carry occurs between bits 3 and 4 of the ALU during an ADD or ADC instruction. It is reset by hardware during the same instructions.

0: No half carry has occurred.

1: A half carry has occurred.

This bit is tested using the JRH or JRNH instruction. The H bit is useful in BCD arithmetic subroutines.



Case 2 Switching from AWU RC to internal RC

- 1. Reset the RC/AWU bit to enable the internal RC oscillator
- 2. Using a 4-bit counter, wait until 8 internal RC cycles have elapsed. The counter is running on internal RC clock.
- 3. Wait till the AWU_FLAG is cleared (1AWU RC cycle) and the RC_FLAG is set (2 RC cycles)
- 4. The switch to the internal RC clock is made at the positive edge of the internal RC clock signal
- 5. Once the switch is made, the AWU RC is stopped
- Note: 1 When the internal RC is not selected, it is stopped so as to save power consumption.
 - 2 When the internal RC is selected, the AWU RC is turned on by hardware when entering Auto wakeup from Halt mode.
 - 3 When the external clock is selected, the AWU RC oscillator is always on.



Figure 9. Clock switching



Figure 10. ST7FOXA0 clock management block diagram

6.2 Multi-oscillator (MO)

The main clock of the ST7 can be generated by four different source types coming from the multi-oscillator block (1 to 16 MHz):

- An external source
- An internal high frequency RC oscillator

6.2.1 External clock source

In this external clock mode, a clock signal (square, sinus or triangle) with ~50% duty cycle has to drive CLKIN.



6.2.2 Internal RC oscillator

In this mode, the tunable RC oscillator is used as main clock source. The two oscillator pins have to be tied to ground.

The calibration is done through the RCCRH[7:0] and RCCRL[6:5] registers.

6.3 Reset sequence manager (RSM)

6.3.1 Introduction

The reset sequence manager includes three RESET sources as shown in Figure 12.

- External RESET source pulse
- Internal LVD RESET (Low Voltage Detection)
- Internal WATCHDOG RESET

A reset can also be triggered following the detection of an illegal op code or prebyte code. Note: Refer to Section 10.2.1 on page 84 for further details.

These sources act on the RESET pin and it is always kept iow during the delay phase.

The RESET service routine vector is fixed at addresser, FFFEh-FFFFh in the ST7 memory mapping.

The basic RESET sequence consists of 3 phases as shown in Figure 11:

- Active Phase depending on the RESET source
- 256 or 512 CPU clock cycle delay (see Table 6)

Caution: When the ST7 is unprogrammed or fully erased, the Flash is blank and the Reset vector is not programmed. For this eason, it is recommended to keep the RESET pin in low state until programming incide is entered, in order to avoid unwanted behavior.

> The 256 or £12 CPU clock cycle delay allows the oscillator to stabilize and ensures that recovery has taken place from the Reset state. The shorter or longer clock cycle delay is automatically selected depending on the clock source chosen by option byte.

Table 6.	CPU clock dela	y during	l Reset se	quence
----------	----------------	----------	------------	--------

-016	The Reset	vector fetch phase duration is 2 clock cycles.	
105	Table 6.	CPU clock delay during Reset sequence	
		Clock source	CPU clock cycle delay
		Internal RC 8 MHz Oscillator	512
		Internal RC 32 kHz Oscillator	256
		External clock connected to CLKIN pin	512



6.5.5 Prescaler register (PSCR)

Reset value: 0000 0011 (03h)

7							0		
CK2	CK1	CK0	0	0	0	1	1		
	Read/write								

Bits 7:5 = CK[2:0] internal RC Prescaler Selection

These bits are set by software and cleared by hardware after a reset. These bits select the prescaler of the internal RC oscillator. See Figure 10: ST7FOXA0 clock management block diagram on page 29 and Table 8.

If the internal RC is used with a supply operating range below 3.3 V, a division ratio of at least 2 must be enabled in the RC prescaler.

Table 8.	Internal	RC	prescaler	selection bit	S
----------	----------	----	-----------	---------------	---

CK2	CK1	СКО	fosc
0	0	1	fh.7/_
0	1	0	fRC/4
0	1	1	f _{RC/8}
1	0	0	f _{RC/16}
	others		f _{RC}

Bits 4:0 = Reserved, must be kept at their reset value.

6.5.6 Clock controller control/status register (CKCNTCSR)

Reset value: UNCC 1001 (09h)

								0
16	0	0	0	0	AWU_FLAG	RC_FLAG	0	RC/AWU
)					Read/write			

Bits 7:4 = Reserved, must be kept cleared.

Bit 3 = AWU_FLAG AWU Selection bit

This bit is set and cleared by hardware.

- 0: No switch from AWU to RC requested
- 1: AWU clock activated and temporization completed

Bit 2 = RC_FLAG RC Selection bit

This bit is set and cleared by hardware.

- 0: No switch from RC to AWU requested
- 1: RC clock activated and temporization completed
- Bit 1 = Reserved, must be kept cleared.



7.2 Slow mode

This mode has two targets:

- To reduce power consumption by decreasing the internal clock in the device,
- To adapt the internal clock frequency (f_{CPU}) to the available supply voltage.

Slow mode is controlled by the SMS bit in the MCCSR register which enables or disables Slow mode.

In this mode, the oscillator frequency is divided by 32. The CPU and peripherals are clocked at this lower frequency.

Note: Slow-Wait mode is activated when entering Wait mode while the device is already in Slow mode.



7.3 Wait mode

Wait mode places the MCU in a low power consumption mode by stopping the CPU.

This power saving mode is selected by calling the 'WFI' instruction.

No oripherals remain active. During Wait mode, the I bit of the CC register is cleared, to enable all interrupts. All other registers and memory remain unchanged. The MCU remains in Wait mode until an interrupt or Reset occurs, whereupon the Program Counter branches to the starting address of the interrupt or Reset service routine.

The MCU will remain in Wait mode until a Reset or an Interrupt occurs, causing it to wake up.

Refer to Figure 18 for a description of the Wait mode flowchart.



Lite Timer Input Capture Register (LTICR)

Reset Value: 0000 0000 (00h)

7							0
ICR7	ICR6	ICR5	ICR4	ICR3	ICR2	ICR1	ICR0
Read only							

Bits 7:0 = ICR[7:0] Input Capture Value

These bits are read by software and cleared by hardware after a reset. If the ICF bit in the LTCSR is cleared, the value of the 8-bit up-counter will be captured when a rising or falling edge occurs on the LTIC pin.

	Table 22.		register	map an	ureset	values				\mathbf{D}
	Address (Hex.)	Register Label	7	6	5	4	3	2	U.	0
	0B	LTCSR Reset Value	ICIE 0	ICF 0	TB 0	TBIE 0	TBF	V/D GHF x	WDGE 0	WDGD 0
	0C	LTICR Reset Value	ICR7 0	ICR6 0	ICR5 0	ICR4. C	OR3 0	ICR2 0	ICR1 0	ICR0 0
opsolete Production										

Table 22. Lite timer register map and reset values



10.2.1 Illegal opcode reset

In order to provide enhanced robustness to the device against unexpected behavior, a system of illegal opcode detection is implemented: a reset is generated if the code to be executed does not correspond to any opcode or prebyte value. This, combined with the Watchdog, allows the detection and recovery from an unexpected fault or interference.

A valid prebyte associated with a valid opcode forming an unauthorized combination does not generate a reset.

Mnemo	Description	Function/Example	Dst	Src	н	I	Ν	Z	С
ADC	Add with Carry	A=A+M+C	А	М	Н		Ν	Z	С
ADD	Addition	A = A + M	А	М	Н		Ν	20	С
AND	Logical And	A = A . M	А	М			N	Z	
BCP	Bit compare A, Memory	tst (A . M)	А	М		0	N	Z	
BRES	Bit Reset	bres Byte, #3	М		く				
BSET	Bit Set	bset Byte, #3	М		1				
BTJF	Jump if bit is false (0)	btjf Byte, #3, Jmp1	М	0					С
BTJT	Jump if bit is true (1)	btjt Byte, #3, Jmp1	М						С
CALL	Call subroutine		n n						
CALLR	Call subroutine relative	0							
CLR	Clear		reg, M				0	1	
CP	Arithmetic Compare	ʻst(B⊴g - M)	reg	М			Ν	Z	С
CPL	One Complement	A = FFH-A	reg, M				Ν	Ζ	1
DEC	Decrement	dec Y	reg, M				Ν	Z	
HALT	ine lt					0			
IRET	Interrupt routine return	Pop CC, A, X, PC			Н	Ι	Ν	Z	С
INC	Increment	inc X	reg, M				Ν	Z	
JP	Absolute Jump	jp [TBL.w]							
URA	Jump relative always								
JRT	Jump relative								
JRF	Never jump	jrf *							
JRIH	Jump if ext. interrupt = 1								
JRIL	Jump if ext. interrupt = 0								
JRH	Jump if H = 1	H = 1 ?							
JRNH	Jump if $H = 0$	H = 0 ?							
JRM	Jump if I = 1	I = 1 ?							
JRNM	Jump if I = 0	I = 0 ?							
JRMI	Jump if N = 1 (minus)	N = 1 ?							

Table 36.Illegal opcode detection

11 Interrupts

The ST7 core may be interrupted by one of two different methods: Maskable hardware interrupts as listed in the "interrupt mapping" table and a non-maskable software interrupt (TRAP). The Interrupt processing flowchart is shown in *Figure 35*.

The maskable interrupts must be enabled by clearing the I bit in order to be serviced. However, disabled interrupts may be latched and processed when they are enabled (see external interrupts subsection).

Note: After reset, all interrupts are disabled.

When an interrupt has to be serviced:

- Normal processing is suspended at the end of the current instruction execution.
- The PC, X, A and CC registers are saved onto the stack.
- The I bit of the CC register is set to prevent additional interrupts.
- The PC is then loaded with the interrupt vector of the interrupt to cervice and the first instruction of the interrupt service routine is fetched (refer to the Interrupt Mapping table for vector addresses).

The interrupt service routine should finish with the IRE T instruction which causes the contents of the saved registers to be recovered from the stack.

Note: As a consequence of the IRET instruction, the 1 bit is cleared and the main program resumes.

Priority management

By default, a servicing interrupt cannot be interrupted because the I bit is set by hardware entering in interrupt routin a.

In the case when se rerai interrupts are simultaneously pending, an hardware priority defines which one vill be serviced first (see the Interrupt Mapping table).

Interrupts and low power mode

All interrupts allow the processor to leave the WAIT low power mode. Only external and concinically mentioned interrupts allow the processor to leave the HALT low power mode (refer to the "Exit from HALT" column in the Interrupt Mapping table).

17.1

Non maskable software interrupt

This interrupt is entered when the TRAP instruction is executed regardless of the state of the I bit. It is serviced according to the flowchart in *Figure 35*.

11.2 External interrupts

External interrupt vectors can be loaded into the PC register if the corresponding external interrupt occurred and if the I bit is cleared. These interrupts allow the processor to leave the HALT low power mode.

The external interrupt polarity is selected through the miscellaneous register or interrupt register (if available).



11.3.1 External Interrupt Control Register 1 (EICR1)

Reset value: 0000 0000 (00h)

7							0
0	0	IS21	IS20	IS11	IS10	IS01	IS00
Read/write							

Bits 7:6 = Reserved, must be kept cleared.

Bits 5:4 = **IS2[1:0]** *ei2* sensitivity bits

These bits define the interrupt sensitivity for ei2 according to Table ?.

Bits 3:2 = IS1[1:0] ei1 sensitivity bits

These bits define the interrupt sensitivity for ei1 according to Table ?.

Bits 1:0 = **IS0[1:0]** *ei0* sensitivity bits

These bits define the interrupt sensitivity for ei0 according to 1ab e?.

- Note: 1 These 8 bits can be written only when the I bit in the CC register is set.
 - 2 Changing the sensitivity of a particular external interrupt of ars this pending interrupt. This can be used to clear unwanted pending interrupts. Fafer to Section : External interrupt function.
 - 3 Whatever the sensitivity configuration ciz cannot exit the MCU from HALT, ACTIVE-HALt and AWUFH modes when a falling ecige occurs.

	ISx1	ISx0	External interrupt sensitivity
	0	0	Falling edge & low level
	0	10	Rising edge only
	10		Falling edge only
	1	1	Rising and falling edge
sole	30		
0/05			



Symbol	Ratings	Maximum value	Unit
I _{VDD}	Total current into V _{DD} power lines (source) ⁽¹⁾	75	
I _{VSS}	Total current out of V_{SS} ground lines (sink) ⁽¹⁾	150	
	Output current sunk by any standard I/O and control pin	20	
I _{IO}	Output current sunk by any high sink I/O pin	40	
	Output current source by any I/Os and control pin	- 25	mA
	Injected current on RESET pin	± 5	
I _{INJ(PIN)} ⁽²⁾⁽³⁾	Injected current on OSC1/CLKIN and OSC2 pins	± 5	\sim
	Injected current on any other pin ⁽⁴⁾	± 5	51
ΣI _{INJ(PIN)} ⁽²⁾	Total injected current (sum of all I/O and control pins) ⁽⁴⁾	<u>a 20</u>	

Table 40. Current characteristics

1. All power (V_DD) and ground (V_SS) lines must always be connected to the cirtemet supply.

I_{INJ(PIN)} must never be exceeded. This is implicitly insured if V_{IN} maximum is respected. If V_{IN} maximum cannot be respected, the injection current must be limited externally to the I_{INJ(PIN)} value. A positive injection is induced by V_{IN}>V_{DD} while a negative injection is induced by V_{IN}<V_{SS}. For true open-drain pads, there is no positive injection current, and the corresponding '_N maximum must always be respected

3. Negative injection disturbs the analog performance of the device. In particular, it induces leakage currents throughout the device including the analog inputs. To avoid undesirable effects on the analog functions, care must be taken:

care must be taken: - Analog input pins must have a negative injection less than 0.8 mA (assuming that the impedance of the analog voltage is lower than the specified mits

- Pure digital pins must have a negative injection less than 1.6 mA. In addition, it is recommended to inject the current as far as possible from the chalog input pins.

4. When several inputs are submitted to a current injection, the maximum Σl_{INJ(PIN)} is the absolute sum of the positive and negative injected currents (instantaneous values). These results are based on characterization with Σl_{INJ(PIN)} maximum current injection on four I/O port pins of the device.

	Table 41.	The.ma characteristics	\$
--	-----------	------------------------	----

	Svmta	Ratings	Value	Unit
	STG	Storage temperature range	-65 to +150	°C
26	TJ	Maximum junction temperature (see <i>Table 66</i> page 121)	6: Thermal characteris	stics on
0050.				



Operating conditions 12.3

12.3.1 **General operating conditions**

 $T_A = -40$ to +85 °C unless otherwise specified.

Table 42. **General operating conditions**

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DD}	Supply voltage	f _{CPU} = 8 MHz max.	4.5	5.5	V
f _{CPU}	CPU clock frequency	4.5 V≤ V _{DD} ≤5.5 V	up	to 8	MHz

12.3.2 **Operating conditions with Low Voltage Detector (LVD)**

Table 43. **Operating characteristics with LVD**

Operating conditions with Low Voltage Detector (LVD)								
$T_A = -40$ to 85 °C unless otherwise specified.								
Table 43.	Operating characteristics with	th LVD		90				
Symbol	Parameter	Conditions	Min	Тур	Max	Unit		
V _{IT+(LVD)}	Reset release threshold (V _{DD} rise)	lete	3.9	4.2	4.5	V		
V _{IT-(LVD)}	Reset generation threshold (V _{DD} fall)	SOID	3.7	4.0	4.3	v		
V _{hys}	LVD voltage threshold hysteresia	V _{IT+(LVD)} -V _{IT-(LVD)}		150		mV		
V _{tPOR}	V _{DD} rise time rate ⁽¹⁾⁽²⁾		2			μs/V		
I _{DD(LVD)}	LVD current consumption	$V_{DD} = 5 V$		80	140	μA		

1. Not tested in production. The V_{DD} rise time rate condition is needed to ensure a correct device power-on and LVD reset release. When the V_{DD} slope is outside these values, the LVD may not release properly the reset of the MC¹.

2. Use of LVD with capacitive power supply: with this type of power supply, if power cuts occur in the application, this recommended to pull V_{DD} down to 0 V to ensure optimum restart conditions. Refer to circuit stanple in *Figure 39 on page 106*. ci Dosolete



12.7.3 Absolute maximum ratings (electrical sensitivity)

Based on two different tests (ESD and LU) using specific measurement methods, the product is stressed in order to determine its performance in terms of electrical sensitivity.

Electrostatic discharge (ESD)

Electrostatic discharges (a positive then a negative pulse separated by 1 second) are applied to the pins of each sample according to each pin combination. The sample size depends on the number of supply pins in the device (3 parts*(n+1) supply pin). Two models can be simulated: Human Body model and Machine model. This test conforms to the JESD22-A114A/A115A standard. For more details, refer to the application note AN1181.

Table 53. ESD absolute maximum ratings

Symbol	Ratings	Conditions	Maxin um vaiu ș ⁽¹⁾	Unit
V _{ESD(HBM)}	Electrostatic discharge voltage (Human Body model)	T _A =+25 °(:	4000	V
V _{ESD(CDM)}	Electrostatic discharge voltage (Charge Device model)	. √4=+52 °C	500	v

1. Data based on characterization results, not tested in production

Static latch-up (LU)

Two complementary static tests are required on six parts to assess the latch-up performance.

- A supply overvoltage is applied to each power supply pin
- A current injection is applied to each input, output and configurable I/O pin.

These tests are comp ian, with the EIA/JESD 78 IC latch-up standard.

Table 54. Electrical sensitivities

	Sym oo'	Parameter	Conditions	Class
	CU	Static latch-up class	T _A = +85 °C	A
Olosole				





Figure 40. RESET pin protection when LVD is disabled

1. The reset network protects the device against parasitic resets.

The output of the external reset circuit must have an open-drain output to drive the ST7 reset p.d. Otherwise the device can be damaged when the ST7 generates an internal reset (LVD or w atchcog). Whatever the reset source is (internal or external), the user must ensure that the level on the RESET pin Whatever the reset source is (internal or external), the user must ensure that the level on the RESET pin can go below the V_{IL} max. level specified in *Section 12.9.1 on page 105*. Otherwise no reset will not be taken into account internally. Because the reset circuit is designed to allow the internal Reset to be output in the RESET pin, the user must ensure that the current sunk on the RESET pin is less than the absolute n aximum value specified for

I_{INJ(RESET)} in Section Table 40. on page 94.

alls or obsolete production Please refer to Section 10.2.1 on page 84 for more details on ille ratio code reset conditions. 2.

107/123



Figure 45. 8-pin plastic dual in-line outline package - 300-mil width, package outline

Table 65.	8-pin plastic dual in-line outline package -	- 30C-יורי width, mechanical data
-----------	--	-----------------------------------

	Symbol	millimeters		inches ⁽¹⁾			
	Symbol	Тур	Min	Max	Тур	Min	Max
	А			5.33			0.2098
	A1		0.38			0.0150	
	A2	3.3	2.92	4.95	0.1299	0.1150	0.1949
	b	0.46	0.36	0.56	0.0181	0.0142	0.0220
	b2	1.52	1.14	1.78	0.0598	0.0449	0.0701
	С	6 25	0.2	0.36	0.0098	0.0079	0.0142
	D	<i>э</i> .27	9.02	10.16	0.3650	0.3551	0.4000
	Ŀ	7.87	7.62	8.26	0.3098	0.3000	0.3252
	E1	6.35	6.1	7.11	0.2500	0.2402	0.2799
26	е	2.54	-	-	0.1000		
SO.	eA	7.62	-	-	0.3000		
$O^{V^{-}}$	eB			10.92			0.4299
	L	3.3	2.92	3.81	0.1299	0.1150	0.1500

1. Values in inches are converted from mm and rounded to 4 decimal digits.